Product Change Notification

103089 - 00

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Product Change Notification

Change Notification #: **103089 - 00**

Change Title: **Intel® E8870 Chipset, PCN 103089-00, FFF, SNCM C0 to C1 Stepping Conversion**

Date of Publication: **February 04, 2003**

Type of Change Notification:

FFF - (Form-Fit-Function)

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date of Samples Availability:	Mar 03, 2003
Date of Qualification Data Availability:	Apr 25, 2003
Date Customer Must be Ready to Receive Post-Conversion Material:	Apr 28, 2003
Date of First Availability of Post-Conversion Material:	Apr 28, 2003

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

The Intel® E8870 Chipset SNCM component is converting from C0 to C1 stepping. With the transition of the SNCM, the E8870 Chipset will also convert to the ICH4 B0 and the P64H2 B1 components at the same time.

For technical details of the Intel® E8870 Chipset, please refer to the latest Spec Update available on FDBL.

Customer Impact of Change and Recommended Action:

The SNCM C1 is pin-to-pin compatible with the C0 and does not require any motherboard modifications. Design changes have been made to the SNCM C1 and will require customers to perform re-qualification.

Please see the latest E8870 Spec Update for any BIOS changes required for the C1 stepping.

Products Affected / Intel Ordering Codes:

Component Product Table

Pre-Conversion Product Code	Pre-Conversion Spec/ROM	Pre-Conversion MM#	Post-Conversion Product Code	Post-Conversion Spec/ROM	Post-Conversion MM#
			KW82870MC	Q E06	850847
KW82870MC	S L5X5	848421	KW82870MC	S L6XR	852616
			FW82801DB	Q D45	848144
FW82801DB	S L66K	844377	FW82801DB	S L6DM	848140
			RG82870P2	Q E03	850722
RG82870P2	S L675	844807	RG82870P2	S L6SU	851130

Reference Documents / Attachments:

Document:	**Location #:**
102546-01	http://fdbl.intel.com/
102768-00	http://fdbl.intel.com/

PCN Revision History:

Date of Revision:	**Revision Number:**	**Reason:**
February 4, 2003	00	Originally Published PCN